

Title (en)

PATTERNED MATERIALS AND FILMS AND SYSTEMS AND METHODS FOR MAKING THE SAME

Title (de)

GEMUSTERTE MATERIALIEN SOWIE FILME UND SYSTEME UND VERFAHREN ZU IHRER HERSTELLUNG

Title (fr)

MATÉRIAUX ET FILMS À MOTIFS ET SYSTÈMES ET PROCÉDÉS POUR LES RÉALISER

Publication

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Application

EP 19852650 A 20190820

Priority

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Abstract (en)

[origin: WO2020041320A1] Disclosed are exemplary embodiments of patterned materials and films (e.g., multilayer films, homogeneous or single layer films, etc.). The films and patterned materials may have controlled and/or tailored performance (e.g., thermal management, electromagnetic interference (EMI) mitigation, electrical conductivity, thermal conductivity, EMI absorbing, magnetic, dielectric, and/or structural performance, etc.). Also disclosed are exemplary embodiments of systems and methods for making such patterned materials and films. In exemplary embodiments, a thermal management and/or electromagnetic interference (EMI) mitigation material comprises a filled dielectric including a pattern of one or more structures protruding outwardly along at least one side of the filled dielectric.

IPC 8 full level

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Citation (search report)

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- [X] JP 2017171773 A 20170928 - JSP CORP, et al
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Designated contracting state (EPC)

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Designated extension state (EPC)

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